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TITLE : SOLDER BONDING METHOD

ABSTRACT : PROBLEM TO BE SOLVED: To obtain a soldering method, which prevents drop in soldering strength and which can ensure a strong soldered part when an electronic component or the like is soldered to an electrode, in which an electroless nickel-phosphorus-plated layer is formed on a metal substrate, such as a copper substrate or the like.

SOLUTION: In this soldering method, an electronic component is soldered, by using tin/lead-based eutectic solder, to an electrode in which an electroless nickel-phosphorus plated layer is formed on a metal substrate or to an electrode, in which a gold-plated layer or a palladium-plated layer is further formed on an electroless nickel-phosphorus plated layer. In the soldering method, as a metal layer which is soldered directly to the electrode, a lead layer or a solder layer whose lead content is higher than the composition of the eutectic solder is precoated, solder is supplied to the precoated metal layer, in such a way that the final composition of a soldering material after the soldering operation of the electronic component lie in the range of the eutectic composition of the tin/lead-based eutectic solder, and the electronic component joint is made.

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